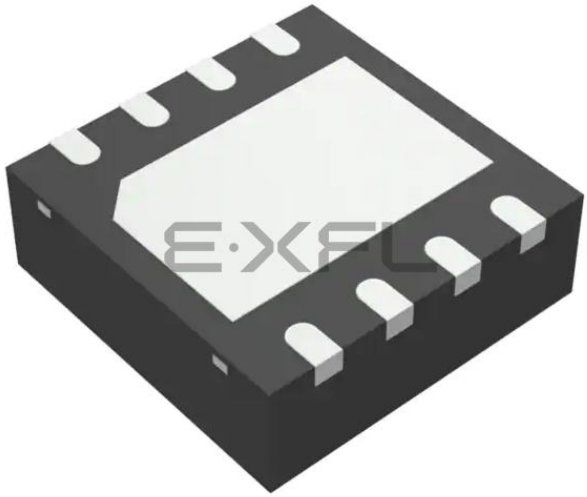

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	5
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN-S (6x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12f629t-e-mf

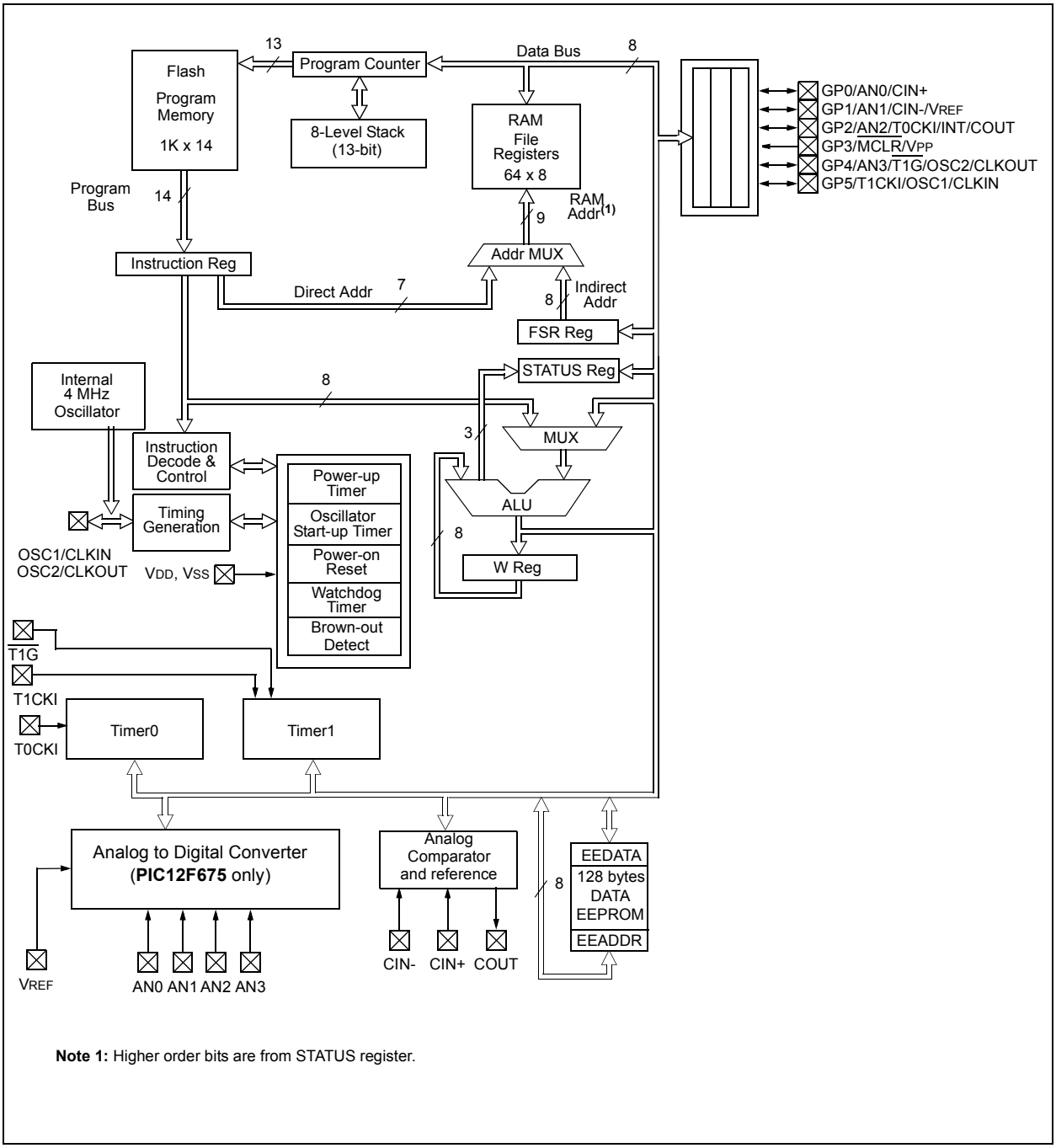
NOTES:

1.0 DEVICE OVERVIEW

This document contains device specific information for the PIC12F629/675. Additional information may be found in the PIC® Mid-Range Reference Manual (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip web site. The Reference Manual should be considered a complementary document to this Data Sheet, and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

The PIC12F629 and PIC12F675 devices are covered by this Data Sheet. They are identical, except the PIC12F675 has a 10-bit A/D converter. They come in 8-pin PDIP, SOIC, MLF-S and DFN packages. Figure 1-1 shows a block diagram of the PIC12F629/675 devices. Table 1-1 shows the pinout description.

FIGURE 1-1: PIC12F629/675 BLOCK DIAGRAM



Note 1: Higher order bits are from STATUS register.

2.2.2.3 INTCON Register

The INTCON register is a readable and writable register, which contains the various enable and flag bits for TMR0 register overflow, GPIO port change and external GP2/INT pin interrupts.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-3: INTCON: INTERRUPT CONTROL REGISTER (ADDRESS: 0Bh OR 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6 **PEIE:** Peripheral Interrupt Enable bit
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts

bit 5 **T0IE:** TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 interrupt
0 = Disables the TMR0 interrupt

bit 4 **INTE:** GP2/INT External Interrupt Enable bit
1 = Enables the GP2/INT external interrupt
0 = Disables the GP2/INT external interrupt

bit 3 **GPIE:** Port Change Interrupt Enable bit(1)
1 = Enables the GPIO port change interrupt
0 = Disables the GPIO port change interrupt

bit 2 **T0IF:** TMR0 Overflow Interrupt Flag bit(2)
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1 **INTF:** GP2/INT External Interrupt Flag bit
1 = The GP2/INT external interrupt occurred (must be cleared in software)
0 = The GP2/INT external interrupt did not occur

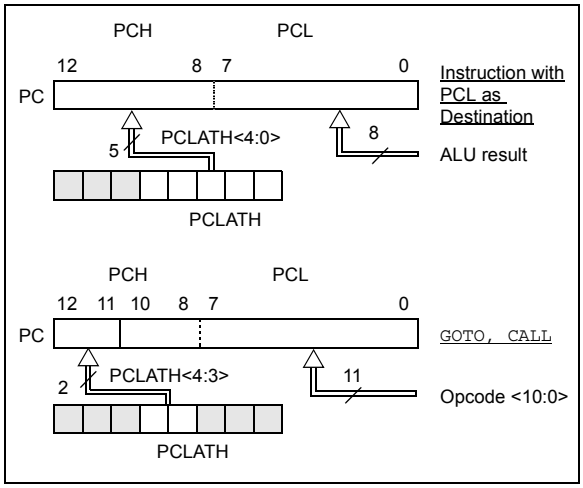
bit 0 **GPIF:** Port Change Interrupt Flag bit
1 = When at least one of the GP5:GP0 pins changed state (must be cleared in software)
0 = None of the GP5:GP0 pins have changed state

Note 1: IOC register must also be enabled to enable an interrupt-on-change.
2: T0IF bit is set when TIMER0 rolls over. TIMER0 is unchanged on Reset and should be initialized before clearing T0IF bit.

2.3 PCL and PCLATH

The Program Counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any Reset, the PC is cleared. Figure 2-3 shows the two situations for the loading of the PC. The upper example in Figure 2-3 shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in Figure 2-3 shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 2-3: LOADING OF PC IN DIFFERENT SITUATIONS



2.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the PC (ADDWF PCL). When performing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block). Refer to the Application Note, *"Implementing a Table Read"* (AN556).

2.3.2 STACK

The PIC12F629/675 family has an 8-level deep x 13-bit wide hardware stack (see Figure 2-1). The stack space is not part of either program or data space and the Stack Pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed, or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no Status bits to indicate Stack Overflow or Stack Underflow conditions.

2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or the vectoring to an interrupt address.

3.0 GPIO PORT

There are as many as six general purpose I/O pins available. Depending on which peripherals are enabled, some or all of the pins may not be available as general purpose I/O. In general, when a peripheral is enabled, the associated pin may not be used as a general purpose I/O pin.

Note:	Additional information on I/O ports may be found in the PIC® Mid-Range Reference Manual, (DS33023).

3.1 GPIO and the TRISIO Registers

GPIO is an 6-bit wide, bidirectional port. The corresponding data direction register is TRISIO. Setting a TRISIO bit (= 1) will make the corresponding GPIO pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISIO bit (= 0) will make the corresponding GPIO pin an output (i.e., put the contents of the output latch on the selected pin). The exception is GP3, which is input-only and its TRISIO bit will always read as '1'. Example 3-1 shows how to initialize GPIO.

Reading the GPIO register reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified, and then written to the PORT data latch. GP3 reads '0' when MCLREN = 1.

The TRISIO register controls the direction of the GP pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISIO register are maintained set when using them as analog inputs. I/O pins configured as analog inputs always read '0'.

Note:	The ANSEL (9Fh) and CMCON (19h) registers (9Fh) must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'. The ANSEL register is defined for the PIC12F675.

EXAMPLE 3-1: INITIALIZING GPIO

```
BCF     STATUS,RP0      ;Bank 0
CLRF    GPIO            ;Init GPIO
MOVLW   07h             ;Set GP<2:0> to
MOVWF   CMCON           ;digital IO
BSF     STATUS,RP0      ;Bank 1
CLRF    ANSEL           ;Digital I/O
MOVLW   0Ch             ;Set GP<3:2> as inputs
MOVWF   TRISIO          ;and set GP<5:4,1:0>
                        ;as outputs
```

3.2 Additional Pin Functions

Every GPIO pin on the PIC12F629/675 has an interrupt-on-change option and every GPIO pin, except GP3, has a weak pull-up option. The next two sections describe these functions.

3.2.1 WEAK PULL-UP

Each of the GPIO pins, except GP3, has an individually configurable weak internal pull-up. Control bits WPUx enable or disable each pull-up. Refer to Register 3-3. Each weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset by the $\overline{\text{GPPU}}$ bit (OPTION<7>).

REGISTER 3-1: GPIO: GPIO REGISTER (ADDRESS: 05h)

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	GPIO5	GPIO4	GPIO3	GPIO2	GPIO1	GPIO0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented**: Read as '0'

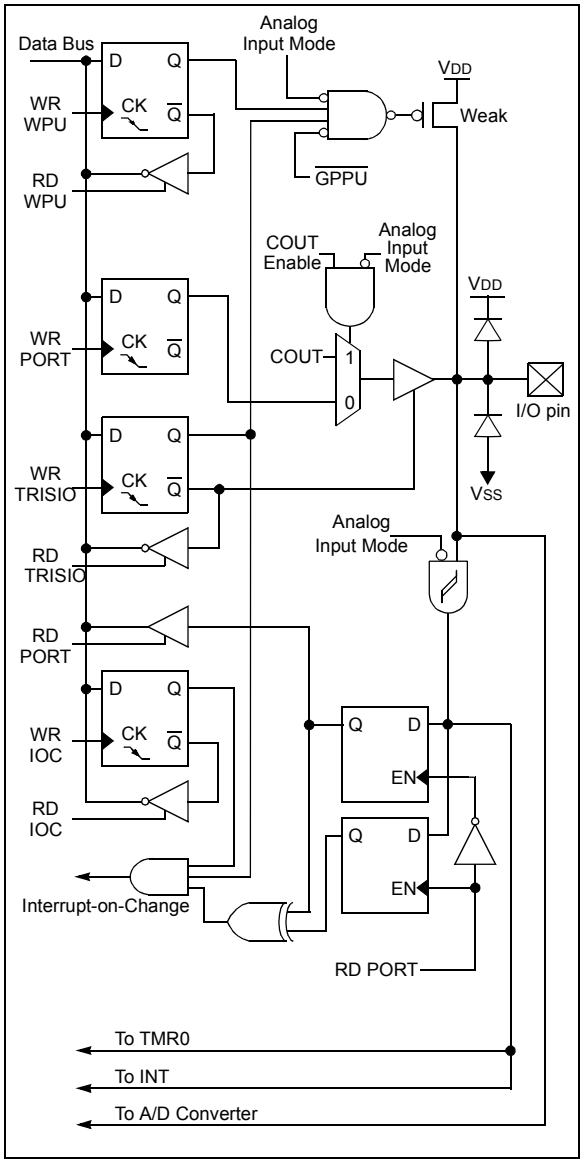
bit 5-0 **GPIO<5:0>**: General Purpose I/O pin
1 = Port pin is >VIH
0 = Port pin is <VIL

3.3.3 GP2/AN2/T0CKI/INT/COUT

Figure 3-2 shows the diagram for this pin. The GP2 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the A/D (PIC12F675 only)
- the clock input for TMR0
- an external edge triggered interrupt
- a digital output from the comparator

FIGURE 3-2: BLOCK DIAGRAM OF GP2

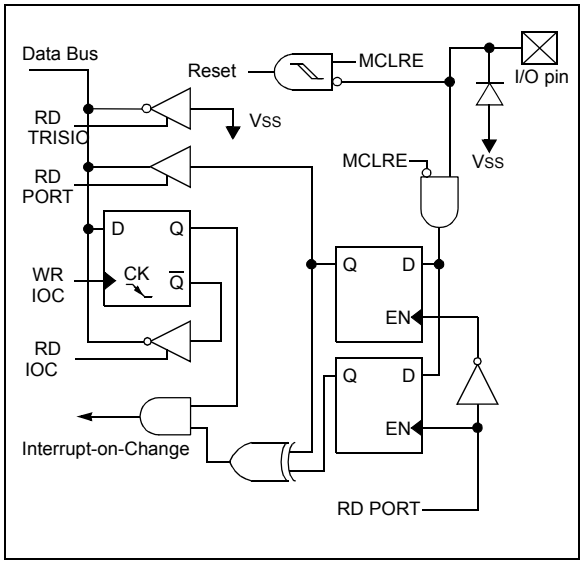


3.3.4 GP3/$\overline{MCLR}$/VPP

Figure 3-3 shows the diagram for this pin. The GP3 pin is configurable to function as one of the following:

- a general purpose input
- as Master Clear Reset

FIGURE 3-3: BLOCK DIAGRAM OF GP3



5.1 Timer1 Modes of Operation

Timer1 can operate in one of three modes:

- 16-bit timer with prescaler
- 16-bit synchronous counter
- 16-bit asynchronous counter

In Timer mode, Timer1 is incremented on every instruction cycle. In Counter mode, Timer1 is incremented on the rising edge of the external clock input T1CKI. In addition, the Counter mode clock can be synchronized to the microcontroller system clock or run asynchronously.

In counter and timer modules, the counter/timer clock can be gated by the $\overline{T1G}$ input.

If an external clock oscillator is needed (and the microcontroller is using the INTOSC w/o CLKOUT), Timer1 can use the LP oscillator as a clock source.

Note:	In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge.

5.2 Timer1 Interrupt

The Timer1 register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When Timer1 rolls over, the Timer1 interrupt flag bit (PIR1<0>) is set. To enable the interrupt on rollover, you must set these bits:

- Timer1 interrupt Enable bit (PIE1<0>)
- PEIE bit (INTCON<6>)
- GIE bit (INTCON<7>).

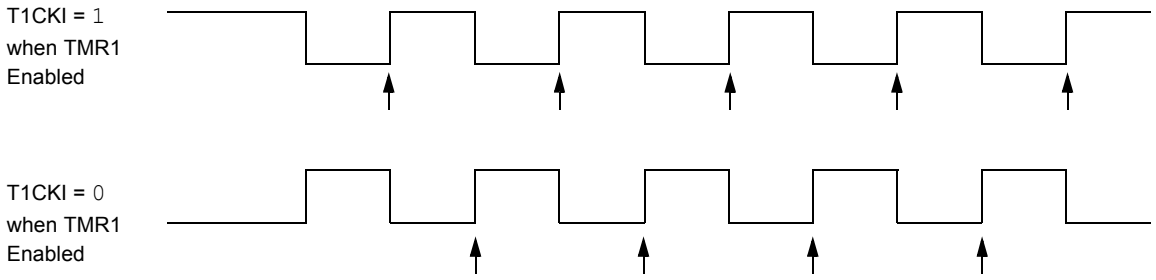
The interrupt is cleared by clearing the TMR1IF in the Interrupt Service Routine.

Note:	The TMR1H:TTMR1L register pair and the TMR1IF bit should be cleared before enabling interrupts.

5.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4, or 8 divisions of the clock input. The T1CKPS bits (T1CON<5:4>) control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

FIGURE 5-2: TIMER1 INCREMENTING EDGE



Note 1: Arrows indicate counter increments.
2: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge of the clock.

5.4 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{\text{T1SYNC}}$ (T1CON<2>) is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (**Section 5.4.1 "Reading and Writing Timer1 in Asynchronous Counter Mode"**).

Note:	The ANSEL (9Fh) and CMCON (19h) registers must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'. The ANSEL register is defined for the PIC12F675.

5.4.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L, while the timer is running from an external asynchronous clock, will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. Examples 12-2 and 12-3 in the PIC® Mid-Range MCU Family Reference Manual (DS33023) show how to read and write Timer1 when it is running in Asynchronous mode.

5.5 Timer1 Oscillator

A crystal oscillator circuit is built-in between pins OSC1 (input) and OSC2 (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low-power oscillator rated up to 37 kHz. It will continue to run during Sleep. It is primarily intended for a 32 kHz crystal. Table 9-2 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is shared with the system LP oscillator. Thus, Timer1 can use this mode only when the system clock is derived from the internal oscillator. As with the system LP oscillator, the user must provide a software time delay to ensure proper oscillator start-up.

While enabled, TRISIO4 and TRISIO5 are set. GP4 and GP5 read '0' and TRISIO4 and TRISIO5 are read '1'.

Note:	The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to enabling Timer1.

5.6 Timer1 Operation During Sleep

Timer1 can only operate during Sleep when setup in Asynchronous Counter mode. In this mode, an external crystal or clock source can be used to increment the counter. To setup the timer to wake the device:

- Timer1 must be on (T1CON<0>)
- TMR1IE bit (PIE1<0>) must be set
- PEIE bit (INTCON<6>) must be set

The device will wake-up on an overflow. If the GIE bit (INTCON<7>) is set, the device will wake-up and jump to the Interrupt Service Routine on an overflow.

TABLE 5-1: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	GPIE	T0IF	INTF	GPIF	0000 0000	0000 000u
0Ch	PIR1	EEIF	ADIF	—	—	CMIF	—	—	TMR1IF	00-- 0--0	00-- 0--0
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON	-000 0000	-uuu uuuu
8Ch	PIE1	EEIE	ADIE	—	—	CMIE	—	—	TMR1IE	00-- 0--0	00-- 0--0

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.

TABLE 7-1: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock Source (TAD)		Device Frequency			
Operation	**ADCS2:ADCS0**	**20 MHz**	**5 MHz**	**4 MHz**	**1.25 MHz**
2 TOSC	000	100 ns(2)	400 ns(2)	500 ns(2)	1.6 μs
4 TOSC	100	200 ns(2)	800 ns(2)	1.0 μs(2)	3.2 μs
8 TOSC	001	400 ns(2)	1.6 μs	2.0 μs	6.4 μs
16 TOSC	101	800 ns(2)	3.2 μs	4.0 μs	12.8 μs(3)
32 TOSC	010	1.6 μs	6.4 μs	8.0 μs(3)	25.6 μs(3)
64 TOSC	110	3.2 μs	12.8 μs(3)	16.0 μs(3)	51.2 μs(3)
A/D RC	x11	2 - 6 μs(1,4)	2 - 6 μs(1,4)	2 - 6 μs(1,4)	2 - 6 μs(1,4)

Legend: Shaded cells are outside of recommended range.

Note 1: The A/D RC source has a typical TAD time of 4 μs for VDD > 3.0V.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When the device frequency is greater than 1 MHz, the A/D RC clock source is only recommended if the conversion will be performed during Sleep.

7.1.5 STARTING A CONVERSION

The A/D conversion is initiated by setting the GO/$\overline{\text{DONE}}$ bit (ADCON0<1>). When the conversion is complete, the A/D module:

- Clears the GO/$\overline{\text{DONE}}$ bit
- Sets the ADIF flag (PIR1<6>)
- Generates an interrupt (if enabled)

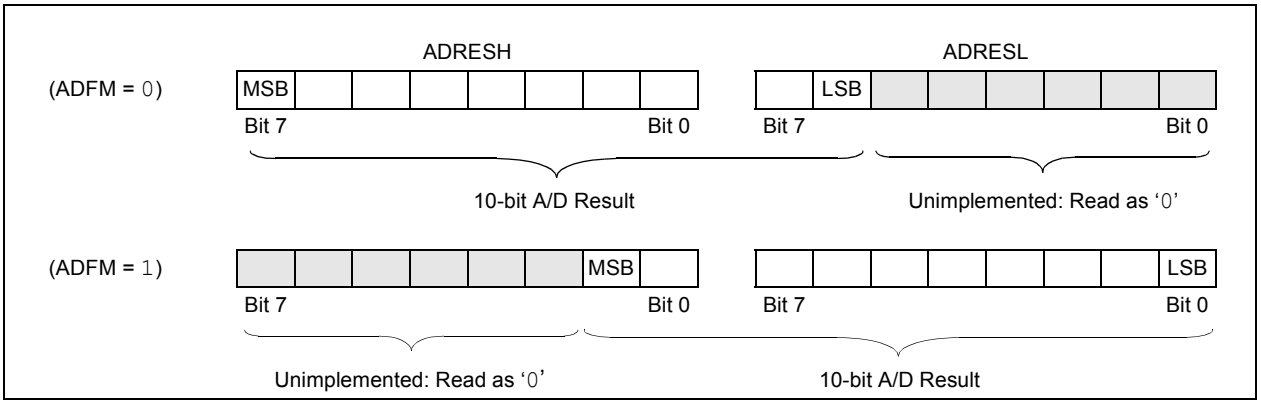
If the conversion must be aborted, the GO/$\overline{\text{DONE}}$ bit can be cleared in software. The ADRESH:ADRESL registers will not be updated with the partially complete A/D conversion sample. Instead, the ADRESH:ADRESL registers will retain the value of the previous conversion. After an aborted conversion, a 2 TAD delay is required before another acquisition can be initiated. Following the delay, an input acquisition is automatically started on the selected channel.

Note:	The GO/$\overline{\text{DONE}}$ bit should not be set in the same instruction that turns on the A/D.

7.1.6 CONVERSION OUTPUT

The A/D conversion can be supplied in two formats: left or right shifted. The ADFM bit (ADCON0<7>) controls the output format. Figure 7-2 shows the output formats.

FIGURE 7-2: 10-BIT A/D RESULT FORMAT



7.2 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-3. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), see Figure 7-3. **The maximum recommended impedance for analog sources is 10 kΩ.** As the impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

To calculate the minimum acquisition time, TACQ, see the PIC® Mid-Range Reference Manual (DS33023).

EQUATION 7-1: ACQUISITION TIME

TACQ = Amplifier Settling Time + Hold Capacitor Charging Time + Temperature Coefficient

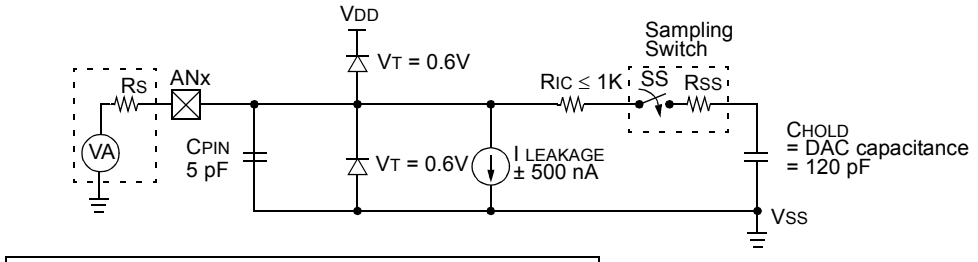
= TAMP + TC + TCOFF
= 2µs + TC + [(Temperature -25°C)(0.05µs/°C)]
TC = CHOLD (RIC + RSS + RS) In(1/2047)
= - 120pF (1kΩ + 7kΩ + 10kΩ) In(0.0004885)
= 16.47µs
TACQ = 2µs + 16.47µs + [(50°C -25°C)(0.05µs/°C)
= 19.72µs

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

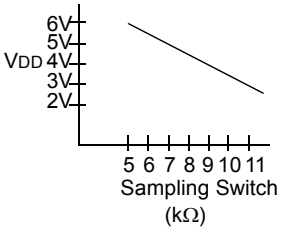
2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

FIGURE 7-3: ANALOG INPUT MODEL



Legend: CPIN = input capacitance; VT = threshold voltage; I LEAKAGE = leakage current at the pin due to various junctions; RIC = interconnect resistance; SS = sampling switch; CHOLD = sample/hold capacitance (from DAC)



XORLW	Exclusive OR Literal with W
Syntax:	[*label*] XORLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) .XOR. k $\rightarrow$ (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.

XORWF	Exclusive OR W with f
Syntax:	[*label*] XORWF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) $\rightarrow$ (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is `0`, the result is stored in the W register. If 'd' is `1`, the result is stored back in register 'f'.

12.2 DC Characteristics: PIC12F629/675-I (Industrial)

		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D010	**Supply Current (IDD)**	—	9	16	µA	2.0	FOSC = 32 kHz LP Oscillator Mode
		—	18	28	µA	3.0	
		—	35	54	µA	5.0	
D011		—	110	150	µA	2.0	FOSC = 1 MHz XT Oscillator Mode
		—	190	280	µA	3.0	
		—	330	450	µA	5.0	
D012		—	220	280	µA	2.0	FOSC = 4 MHz XT Oscillator Mode
		—	370	650	µA	3.0	
		—	0.6	1.4	mA	5.0	
D013		—	70	110	µA	2.0	FOSC = 1 MHz EC Oscillator Mode
		—	140	250	µA	3.0	
		—	260	390	µA	5.0	
D014		—	180	250	µA	2.0	FOSC = 4 MHz EC Oscillator Mode
		—	320	470	µA	3.0	
		—	580	850	µA	5.0	
D015		—	340	450	µA	2.0	FOSC = 4 MHz INTOSC Mode
		—	500	700	µA	3.0	
		—	0.8	1.1	mA	5.0	
D016		—	180	250	µA	2.0	FOSC = 4 MHz EXTRC Mode
		—	320	450	µA	3.0	
		—	580	800	µA	5.0	
D017		—	2.1	2.95	mA	4.5	FOSC = 20 MHz HS Oscillator Mode
		—	2.4	3.0	mA	5.0	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

12.4 DC Characteristics: PIC12F629/675-E (Extended)

		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended					
Param No.	Device Characteristics	Min	Typ†	Max	Units	Conditions	
						VDD	Note
D010E	**Supply Current (IDD)**	—	9	16	μA	2.0	FOSC = 32 kHz LP Oscillator Mode
		—	18	28	μA	3.0	
		—	35	54	μA	5.0	
D011E		—	110	150	μA	2.0	FOSC = 1 MHz XT Oscillator Mode
		—	190	280	μA	3.0	
		—	330	450	μA	5.0	
D012E		—	220	280	μA	2.0	FOSC = 4 MHz XT Oscillator Mode
		—	370	650	μA	3.0	
		—	0.6	1.4	mA	5.0	
D013E		—	70	110	μA	2.0	FOSC = 1 MHz EC Oscillator Mode
		—	140	250	μA	3.0	
		—	260	390	μA	5.0	
D014E		—	180	250	μA	2.0	FOSC = 4 MHz EC Oscillator Mode
		—	320	470	μA	3.0	
		—	580	850	μA	5.0	
D015E		—	340	450	μA	2.0	FOSC = 4 MHz INTOSC Mode
		—	500	780	μA	3.0	
		—	0.8	1.1	mA	5.0	
D016E		—	180	250	μA	2.0	FOSC = 4 MHz EXTRC Mode
		—	320	450	μA	3.0	
		—	580	800	μA	5.0	
D017E		—	2.1	2.95	mA	4.5	FOSC = 20 MHz HS Oscillator Mode
		—	2.4	3.0	mA	5.0	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

12.8 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp			
cc	CCP1	osc	OSC1
ck	CLKOUT	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T1CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$

Uppercase letters and their meanings:

S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-Impedance)	V	Valid
L	Low	Z	High-Impedance

FIGURE 12-4: LOAD CONDITIONS

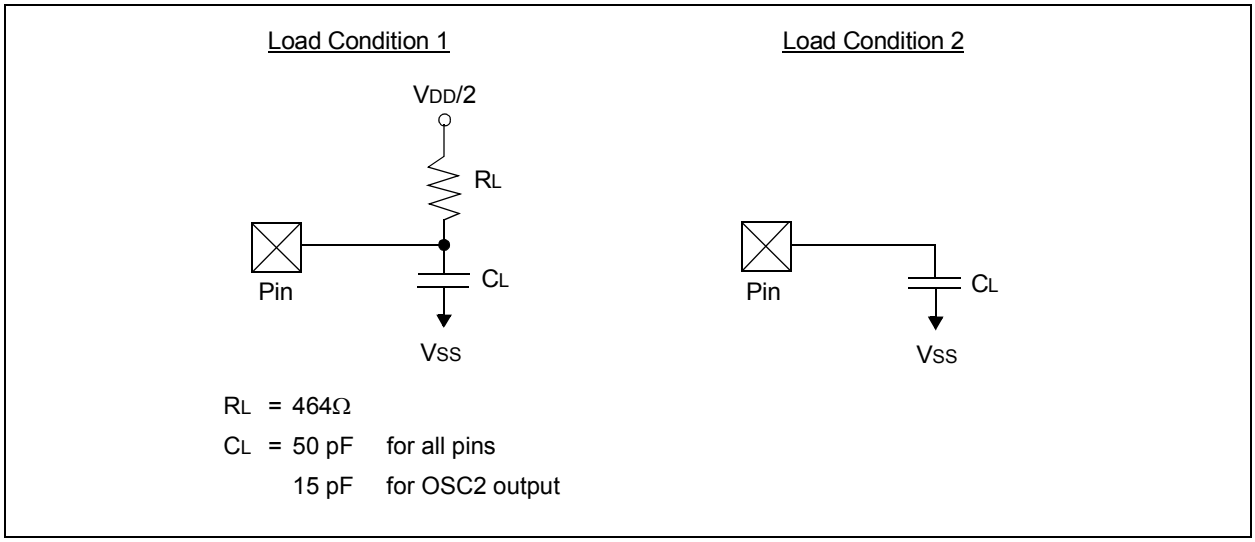


FIGURE 12-7: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

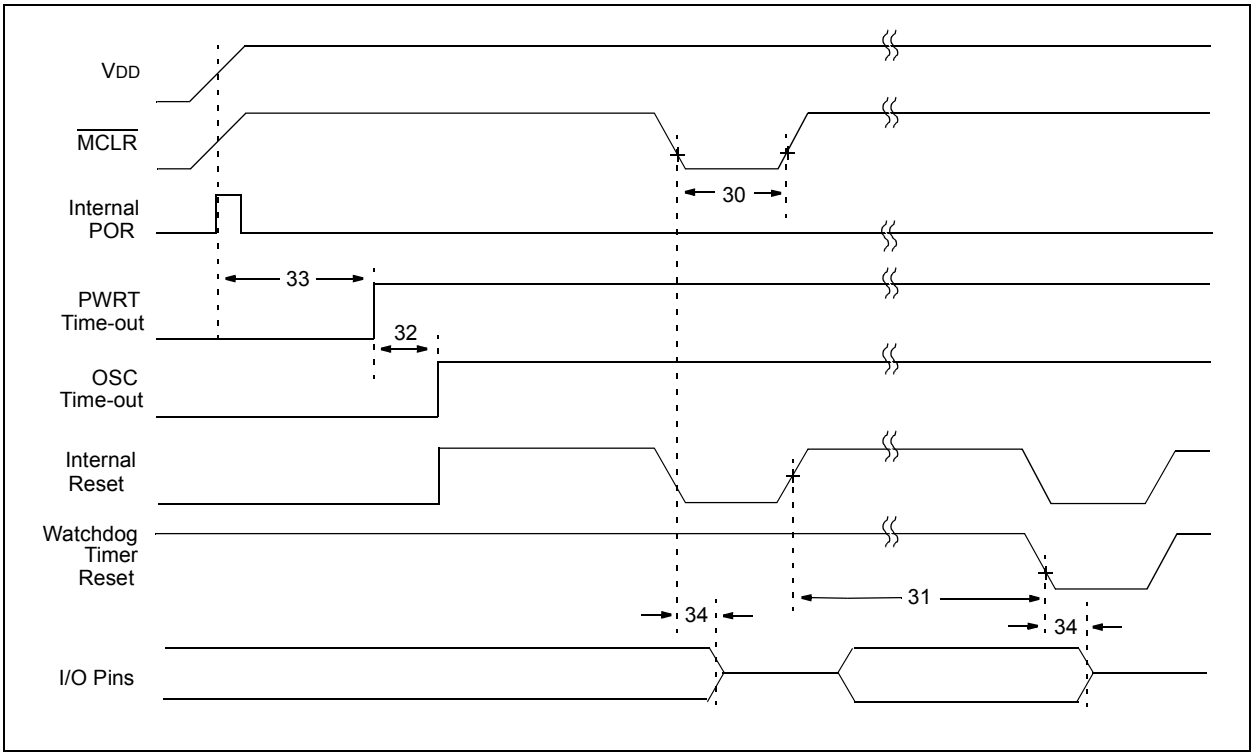
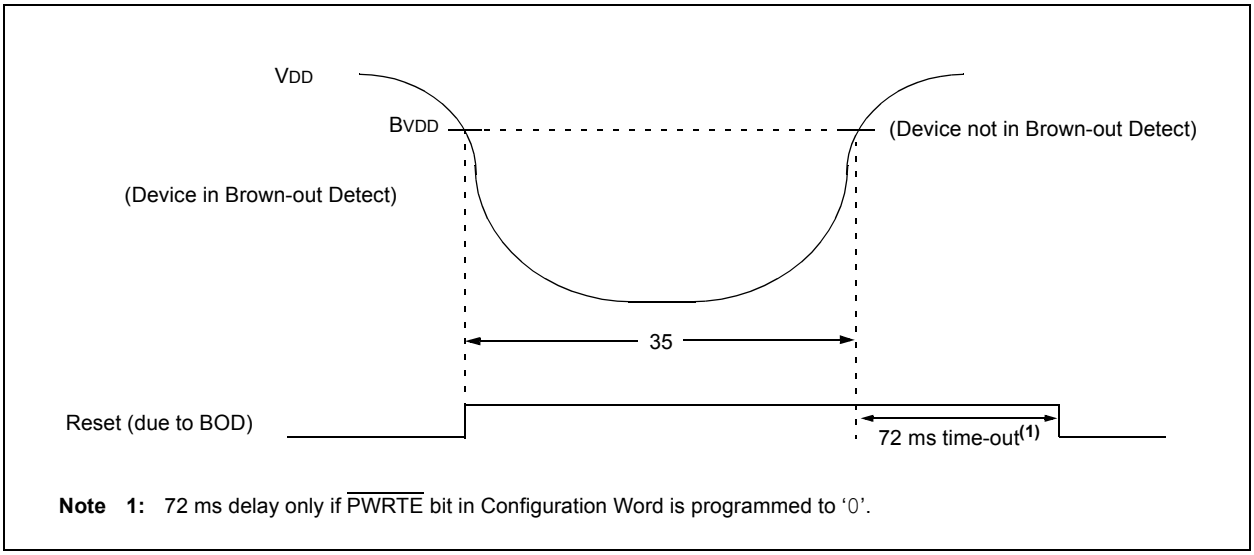


FIGURE 12-8: BROWN-OUT DETECT TIMING AND CHARACTERISTICS



Note 1: 72 ms delay only if $\overline{\text{PWRTE}}$ bit in Configuration Word is programmed to '0'.

FIGURE 12-9: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

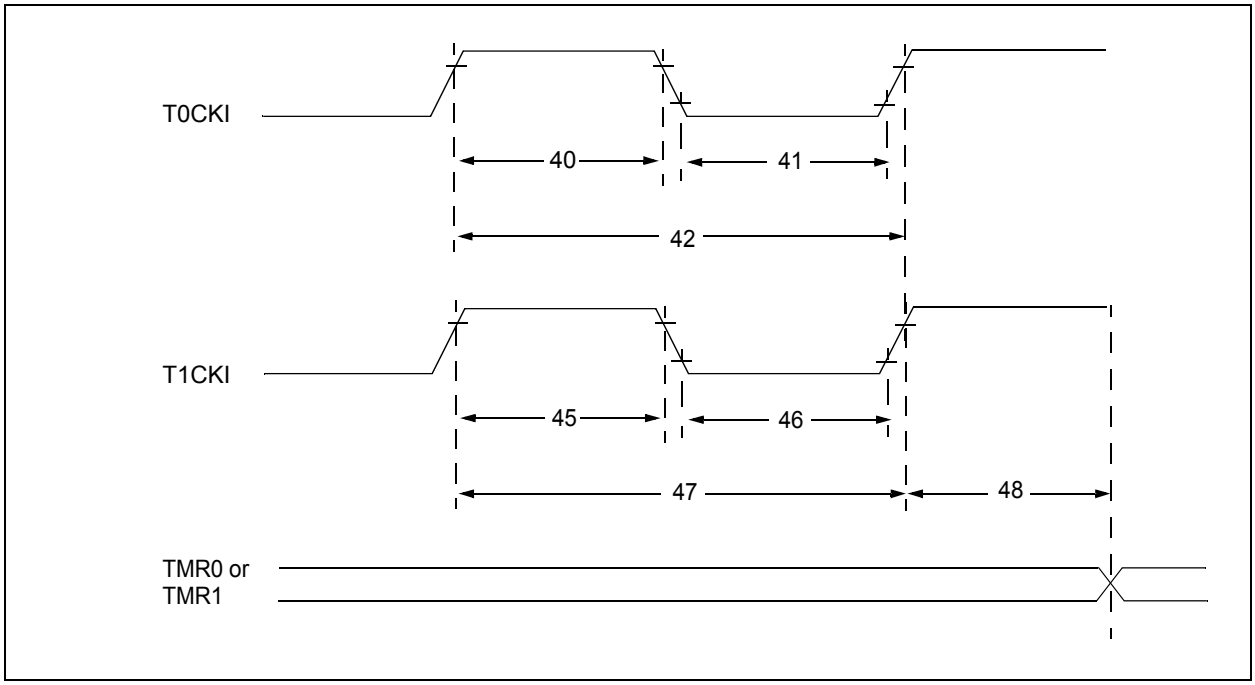


TABLE 12-5: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period		Greater of: 20 or TCY + 40 / N	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	Tt1H	T1CKI High Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
47*	Tt1P	T1CKI Input Period	Synchronous	Greater of: 30 or TCY + 40 / N	—	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous	60	—	—	ns	
	Ft1	Timer1 oscillator input frequency range (oscillator enabled by setting bit T1OSCEN)		DC	—	200*	kHz	
48	TCKEZtmr1	Delay from external clock edge to timer increment		2 TOSC*	—	7 TOSC*	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 13-15: MAXIMUM AND MINIMUM INTOSC FREQ vs. TEMPERATURE WITH 0.1μF AND 0.01μF DECOUPLING (V_{DD} = 3.5V)

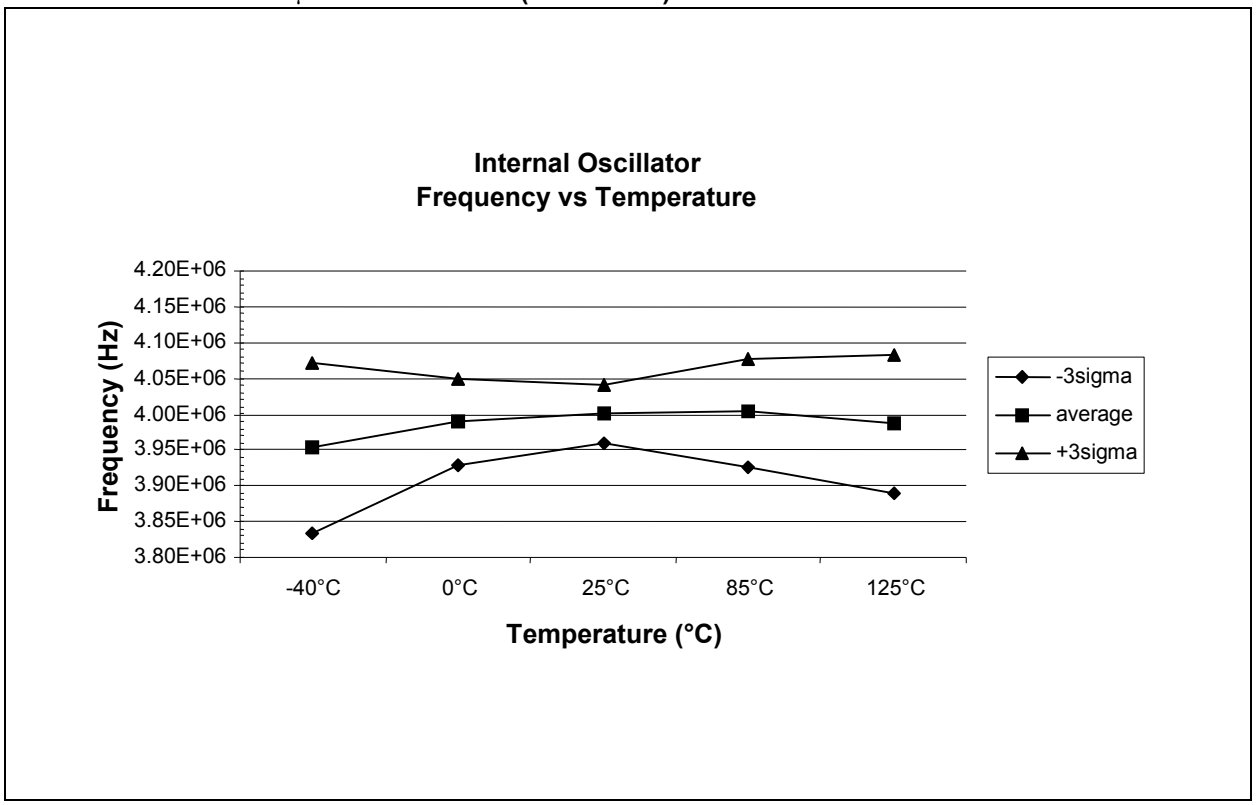
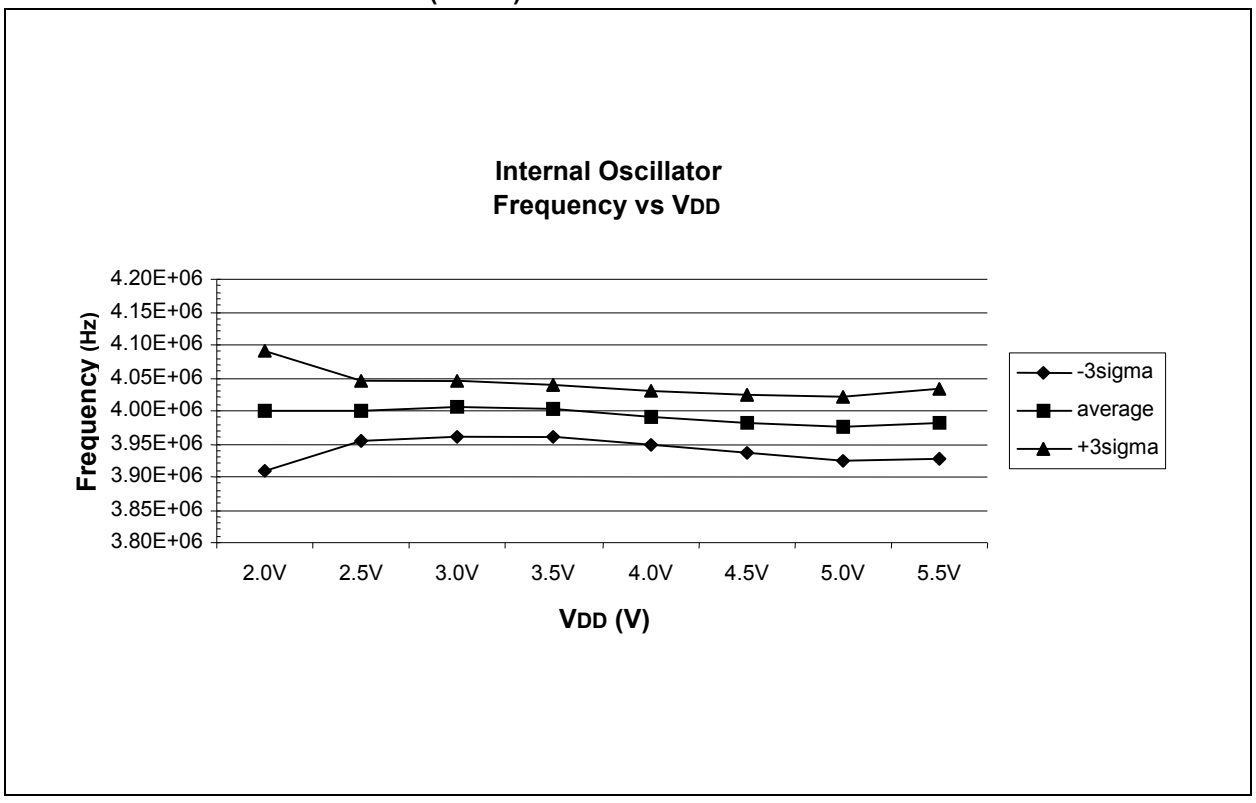
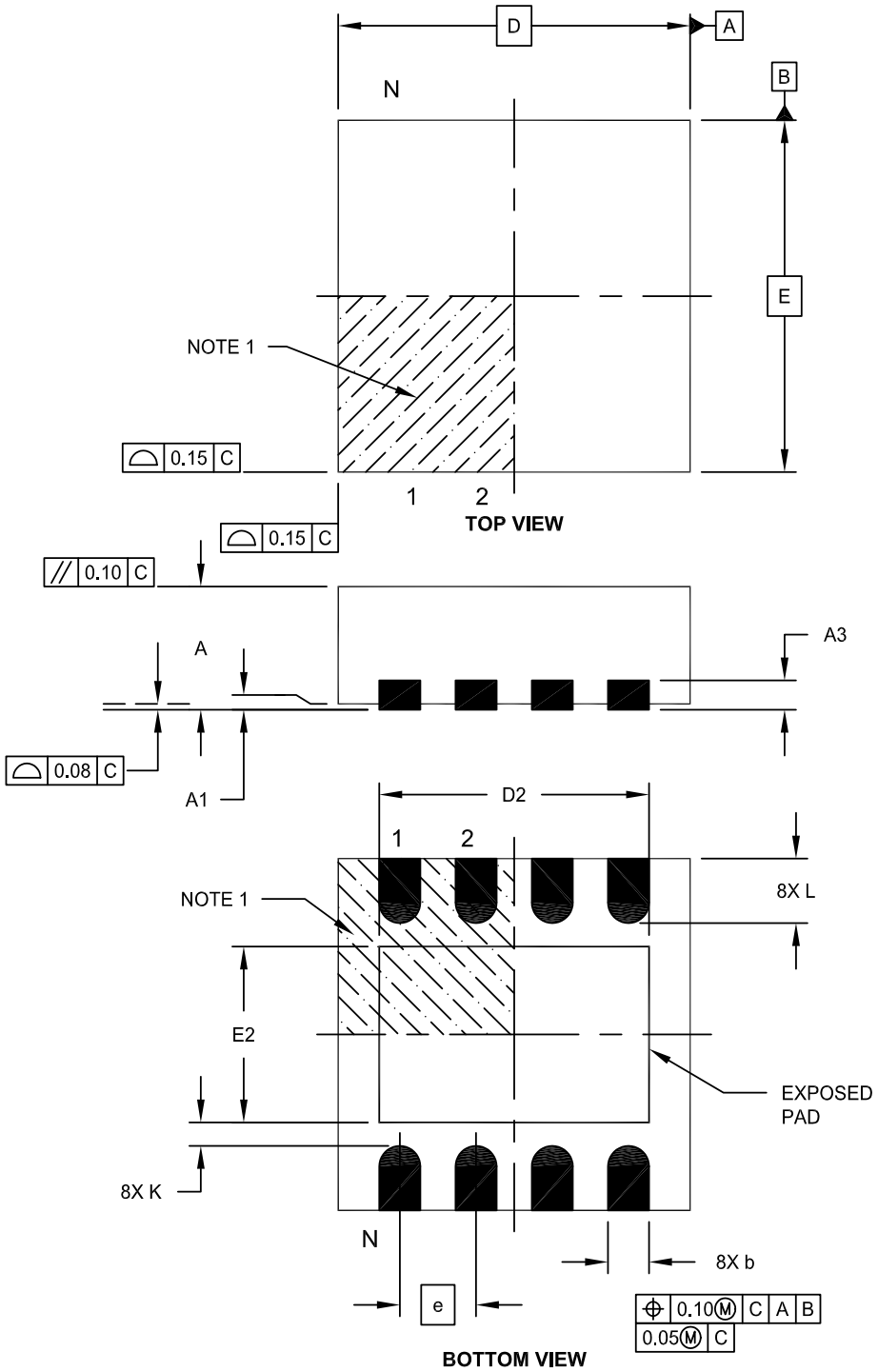


FIGURE 13-16: MAXIMUM AND MINIMUM INTOSC FREQ vs. V_{DD} WITH 0.1μF AND 0.01μF DECOUPLING (+25°C)



8-Lead Plastic Dual Flat, No Lead Package (MD) – 4x4x0.9 mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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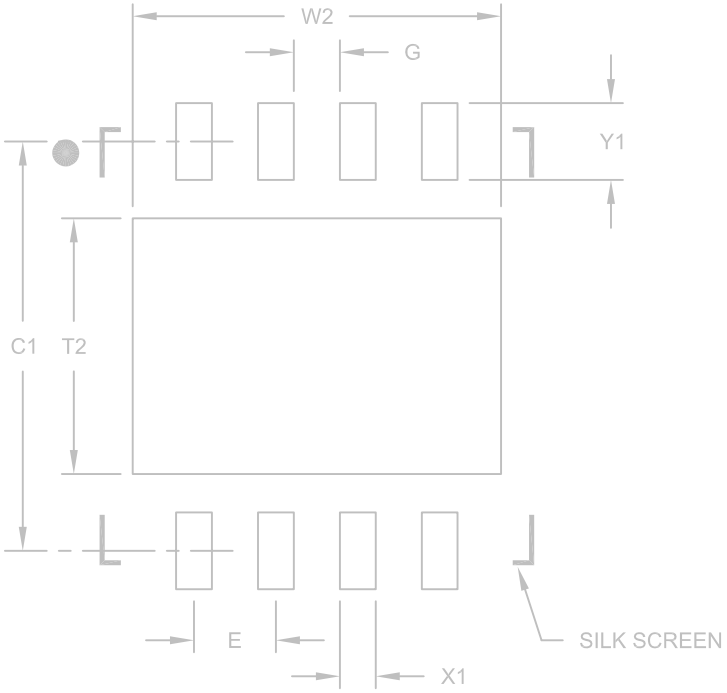
8-Lead Plastic Dual Flat, No Lead Package (MD) – 4x4x0.9 mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.80 BSC	
Optional Center Pad Width	W2			3.60
Optional Center Pad Length	T2			2.50
Contact Pad Spacing	C1		4.00	
Contact Pad Width (X8)	X1			0.35
Contact Pad Length (X8)	Y1			0.75
Distance Between Pads	G	0.45		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2131B

V

W